














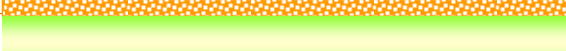



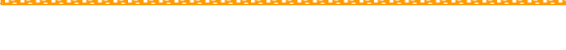
**Schematic Key for Multilayer and HDI-Technology Build-Ups**

a	b	c	d	e	f	g + h + i
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**10 135 FR4 35 L10.35 P06**

columns and equal kind of positions are separated by "\_". Equal prefixes in one column are reduced to one.

**10\_135\_FR4\_35\_L10.35\_p06**

Layers	in $\mu$	Material	Build-Up	Assembly	
<b>Layer-1</b>	35 $\mu$	Copper		} <b>A1</b>	
	60 $\mu$	Prepreg			<b>(60<math>\mu</math> PrePreg-Type: 1080)</b>
	60 $\mu$	Prepreg			
<b>Layer-2</b>	35 $\mu$	Copper			} <b>A2</b>
	100 $\mu$	L-FR4			
<b>Layer-3</b>	35 $\mu$	Copper			
	60 $\mu$	Prepreg			
<b>Layer-4</b>	60 $\mu$	Prepreg			
	35 $\mu$	Copper			
<b>Layer-5</b>	100 $\mu$	L-FR4		} <b>A3</b>	
	35 $\mu$	Copper			
<b>Layer-6</b>	60 $\mu$	Prepreg			
	60 $\mu$	Prepreg			
<b>Layer-7</b>	35 $\mu$	Copper		} <b>A4</b>	
	100 $\mu$	L-FR4			
<b>Layer-8</b>	35 $\mu$	Copper			
	60 $\mu$	Prepreg			
<b>Layer-9</b>	60 $\mu$	Prepreg			
	35 $\mu$	Copper			
<b>Layer-99</b>	100 $\mu$	L-FR4			} <b>B</b>
	35 $\mu$	Copper			
	60 $\mu$	Prepreg			
60 $\mu$	Prepreg				
35 $\mu$	Copper				

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